Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A semiconductor module comprising:

a semiconductor chip having a first surface and a second surface;

a first electrode plate contacting the first surface of the semiconductor chip;

a second electrode plate contacting the second surface of the semiconductor chip; and

a resin mold for sealing the first and second electrode plates and the semiconductor chip, wherein:

~~wherein~~ the resin mold includes an inner pressure release portion that passes from an interior of the resin mold to an exterior of the resin mold for releasing an inner pressure in the ~~resin mold.~~ resin mold, and the resin mold seals a surface of the semiconductor chip, and

wherein the inner pressure release portion is provided by a hole, which extends from the surface of the semiconductor chip to outside of the resin mold.

2. (Original) The module according to claim 1,

wherein the first electrode plate includes a first electrode and a signal terminal, which protrude from the resin mold, and

wherein the second electrode plate includes a second electrode, which protrudes from the resin mold.

3. (Previously Presented) The module according to claim 1,

wherein the inner pressure rises in the resin mold in a case when a temperature of the semiconductor chip increases.

4. (Original) The module according to claim 1,

wherein the first electrode plate includes a body, which is exposed outside of the resin mold, and

wherein the second electrode plate includes a body, which is exposed outside of the resin mold.

5. (Original) The module according to claim 1,

wherein the semiconductor chip is sandwiched by the first and second electrode plates, and embedded in the resin mold.

6. (Original) The module according to claim 1,

wherein the inner pressure release portion is made of resin material having low adhesiveness to the resin mold, and

wherein the inner pressure release portion is a resin rod embedded in the resin mold.

7. (Original) The module according to claim 6,

wherein the resin rod extends from a surface of the semiconductor chip to outside of the resin mold.

8. (Original) The module according to claim 7,

wherein the resin mold includes a hole,

wherein the resin rod is inserted into the hole of the resin mold, and

wherein the resin rod is removable from the hole so that a clearance is formed between the resin rod and the hole.

9. (Original) The module according to claim 8,

wherein the inner pressure release portion works in such a manner that the inner pressure in the resin mold is released through the clearance between the resin rod and the hole.

10. (Original) The module according to claim 8,

wherein the resin rod is capable of being pushed out of the hole.

11. (Original) The module according to claim 10,

wherein the inner pressure release portion works in such a manner that the inner pressure in the resin mold is released through the hole after the resin rod drops out of the hole.

12. (Currently Amended) A semiconductor module comprising:

a semiconductor chip having a first surface and a second surface;

a first electrode plate contacting the first surface of the semiconductor chip;

a second electrode plate contacting the second surface of the semiconductor chip; and

a resin mold for sealing the first and second electrode plates and the semiconductor chip, wherein:

~~wherein~~ each of the first and second electrode plates includes an inner pressure release portion that passes from an interior of the resin mold to an exterior of the resin mold for releasing an inner pressure in the ~~resin mold.~~ resin mold, and

the resin mold seals a surface of the semiconductor chip, and wherein the inner pressure release portion is provided by a groove, which extends from the surface of the semiconductor chip to outside of the resin mold.

13. (Original) The module according to claim 12,

wherein the first electrode plate includes a first electrode and a signal terminal, which protrude from the resin mold, and

wherein the second electrode plate includes a second electrode, which protrudes from the resin mold.

14. (Original) The module according to claim 12,

wherein the inner pressure arises in the resin mold in a case where the semiconductor chip works in abnormal operations.

15. (Original) The module according to claim 12,

wherein the first electrode plate includes a body, which is exposed outside of the resin mold, and

wherein the second electrode plate includes a body, which is exposed outside of the resin mold.

16. (Original) The module according to claim 12,

wherein the semiconductor chip is sandwiched by the first and second electrode plates, and embedded in the resin mold.

17. (Original) The module according to claim 12,

wherein the inner pressure release portion is a starting point for deforming the first and second electrode plates so that the inner pressure is released.

18. (Currently Presented) The module according to claim 17,

wherein the starting point does not overlap the semiconductor chips.

19. (Original) The module according to claim 17,

wherein each of the first and second electrode plates includes the starting point and an other portion, and

wherein the other portion is deformable so that a clearance is formed between the other portion and the resin mold.

20. (Original) The module according to claim 19,

wherein the inner pressure release portion works in such a manner that the inner pressure in the resin mold is released through the clearance.

21. (Original) The module according to claim 17,

wherein the inner pressure release portion is a concavity or a convexity for deforming the first and second electrode plates so that the inner pressure is released.